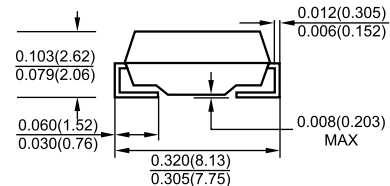
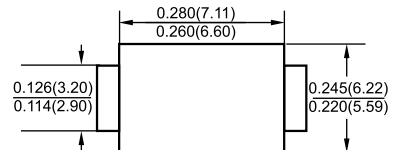




Features

- ✦ For surface mounted application
- ✦ Glass passivated junction chip.
- ✦ Low forward voltage drop
- ✦ High current capability
- ✦ Easy pick and place
- ✦ High surge current capability
- ✦ Plastic material used carries Underwriters Laboratory Classification 94V-0
- ✦ High temperature soldering: 260°C / 10 seconds at terminals

SMC/DO-214AB



Dimensions in inches and (millimeters)

Mechanical Data

- ✦ Case: Molded plastic
- ✦ Terminals: Pure tin plated, lead free.
- ✦ Polarity: Indicated by cathode band
- ✦ Weight: 0.21 gram

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	S3AC	S3BC	S3DC	S3GC	S3JC	S3KC	S3MC	Units
Marking code		S3A	S3B	S3D	S3G	S3J	S3K	S3M	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ $T_L = 105^\circ\text{C}$	$I_{(AV)}$	3.0							A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	100							A
Maximum Instantaneous Forward Voltage @ 3.0A	V_F	1.15							V
Maximum DC Reverse Current @ $T_A = 25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	I_R	10.0 250							μA μA
Typical Reverse Recovery Time (Note 1)	T_{rr}	1.5							μs
Typical Junction Capacitance (Note 2)	C_j	60							pF
Typical Thermal Resistance (Note 3)	$R_{\theta JL}$ $R_{\theta JA}$	13 47							$^\circ\text{C/W}$
Operating Temperature Range	T_J	-55 to +150							$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150							$^\circ\text{C}$

- Notes:
1. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$
 2. Measured at 1 MHz and Applied $V_R=4.0$ Volts
 3. Measured on P.C. Board with 0.4" x 0.4" (10mm x 10mm) Copper Pad Areas.



RATINGS AND CHARACTERISTIC CURVES

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

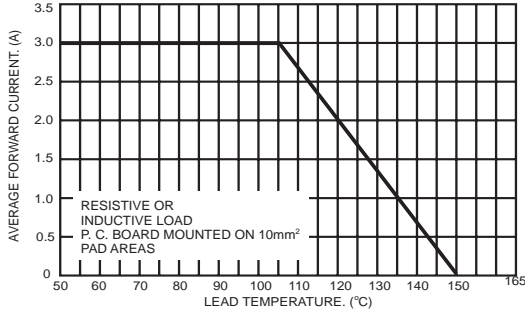


FIG.2- TYPICAL REVERSE CHARACTERISTICS

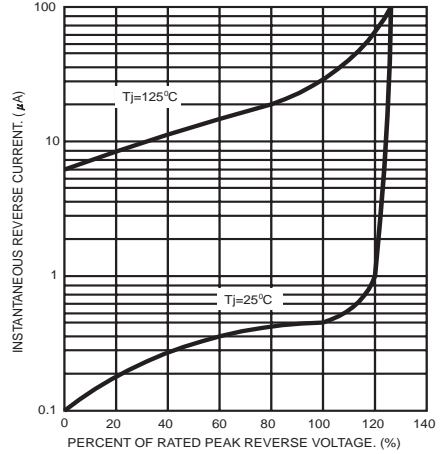


FIG.3- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

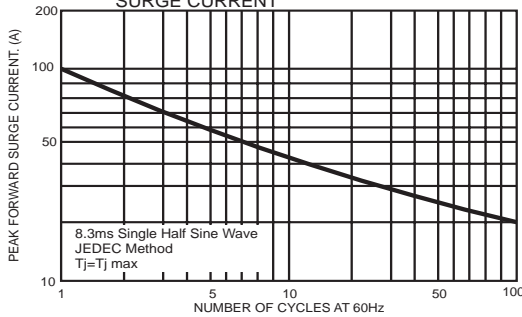


FIG.5- TYPICAL FORWARD CHARACTERISTICS

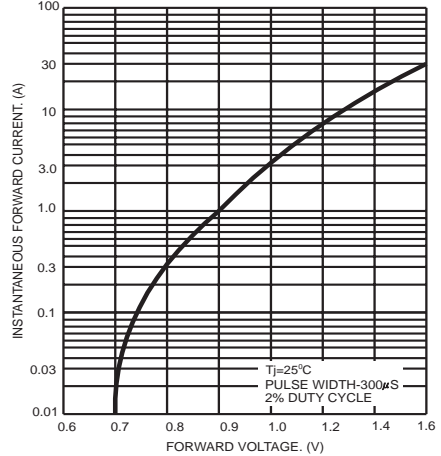


FIG.4- TYPICAL JUNCTION CAPACITANCE

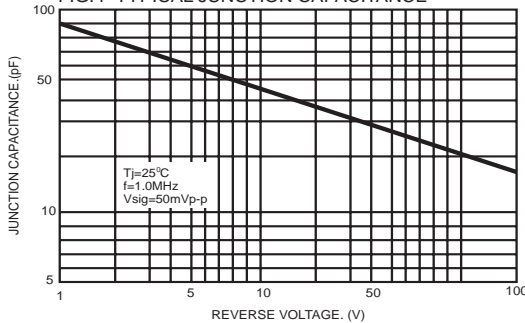
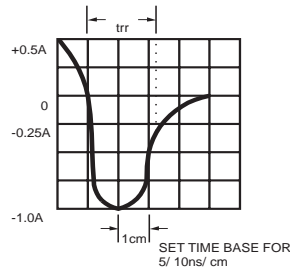
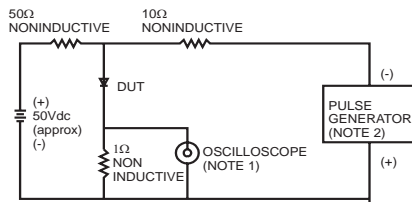


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



NOTES: 1. Rise Time=7ns max. Input Impedance= 1 megohm 22pf
2. Rise Time=10ns max. Source Impedance= 50 ohms

PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMC	3000/REEL	42000	36X36X36.5	18.50	15.50